

## ABSTRACT

Electroplating in device making. Development of technological process galvanic precipitation of tin on the conductive pattern of the printed circuit board assembly.

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Diploma project, 2015. Amount of pages - 86, tables - 27,

Pictures - 3, drafts - 2, literary sources - 17.

In the project the workflow galvanic deposition of tin coatings on conductive pattern of the printed circuit board assembly using sulfate electrolyte with additives such STH Zusatz and Suffotech SP is designed. This electrolyte is characterized by high scattering ability, uniform distribution of copper on the surface of the board, regardless of its size and picture conductors sedimentation of plastic, very strong layer with low internal tensions. For electroplating galvanic bath with a capacity of 86 000 units/year was selected and designed .

The project envisages measures for safety and automation of process parameters, method of sewage treatment by reagent method proposed was propered designed the main technical and economic indicators was designed.

**Keywords** : printed circuit boards, tin coating application, sulfate electrolyte, metallorезист, conductive pattern, wastewater, automation of process parameters

					ДП ХЕ 1118.1450.00.000 ПЗ	Арк.
						7
Вит.	Арк.	№ докум.	Підпис	Дата		